

## High Speed Infrared Emitting Diode, 940 nm, GaAlAs Double Hetero



21531

### DESCRIPTION

VSMB1940ITX01 is an infrared, 940 nm emitting diode in GaAlAs double hetero technology with high radiant power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

### FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Enhanced operating temperature range: -40 °C to +105 °C
- Peak wavelength:  $\lambda_p = 940$  nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity:  $\phi = \pm 60^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 72 h, MSL 4, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE  
GRADE

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
**GREEN**  
(5-2008)

### APPLICATIONS

- IR emitter for automotive applications
- High power emitter for low space applications
- High performance transmissive or reflective sensors

### PRODUCT SUMMARY

COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMB1940ITX01	6	$\pm 60$	940	15

#### Note

- Test conditions see table "Basic Characteristics"

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB1940ITX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

#### Note

- MOQ: minimum order quantity

### ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25$ °C, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5$ , $t_p = 100$ $\mu$ s	$I_{FM}$	200	mA
Surge forward current	$t_p = 100$ $\mu$ s	$I_{FSM}$	1	A
Power dissipation		$P_V$	160	mW
Junction temperature		$T_j$	110	°C
Operating temperature range		$T_{amb}$	-40 to +105	°C
Storage temperature range		$T_{stg}$	-40 to +110	°C
Soldering temperature	According to reflow profile Fig. 9	$T_{sd}$	260	°C
Thermal resistance junction / ambient	JESD 51	$R_{thJA}$	270	K/W

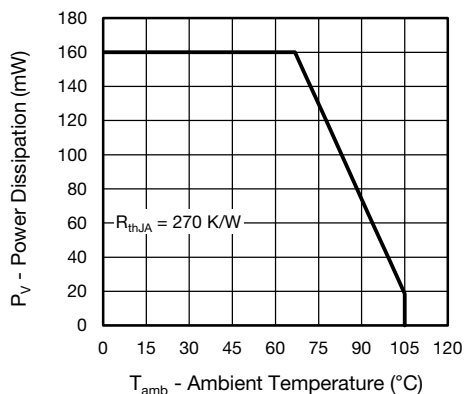


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

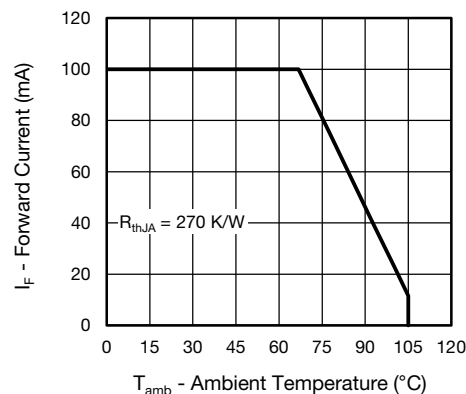


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$V_F$	1.15	1.35	1.6	V
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$V_F$	-	2.2	-	V
Temperature coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{VF}$	-	-1.5	-	mV/K
	$I_F = 100\text{ mA}$	$TK_{VF}$	-	-1.1	-	mV/K
Reverse current	$V_R = 5\text{ V}$	$I_R$	-	-	10	$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ mW/cm}^2$	$C_J$	-	70	-	pF
Radiant intensity	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$I_e$	3	6	12	mW/sr
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$I_e$	-	60	-	mW/sr
Radiant power	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$\phi_e$	-	40	-	mW
Temperature coefficient of radiant power	$I_F = 1\text{ mA}$	$TK_{\phi_e}$	-	-1.1	-	%/K
	$I_F = 100\text{ mA}$	$TK_{\phi_e}$	-	-0.51	-	%/K
Angle of half intensity		$\phi$	-	$\pm 60$	-	deg
Peak wavelength	$I_F = 30\text{ mA}$	$\lambda_p$	-	940	-	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$	-	25	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 30\text{ mA}$	$TK_{\lambda_p}$	-	0.25	-	nm
Rise time	$I_F = 100\text{ mA}$ , 20 % to 80 %	$t_r$	-	15	-	ns
Fall time	$I_F = 100\text{ mA}$ , 20 % to 80 %	$t_f$	-	15	-	ns
Virtual source diameter		$d$	-	0.5	-	mm



**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

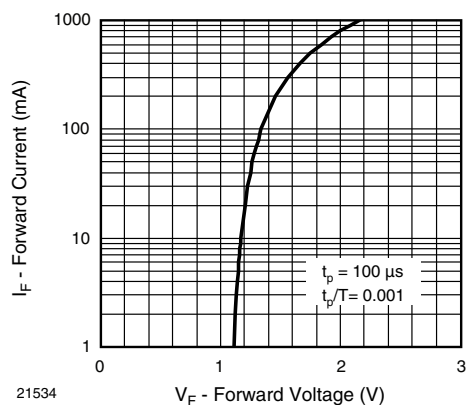


Fig. 3 - Forward Current vs. Forward Voltage

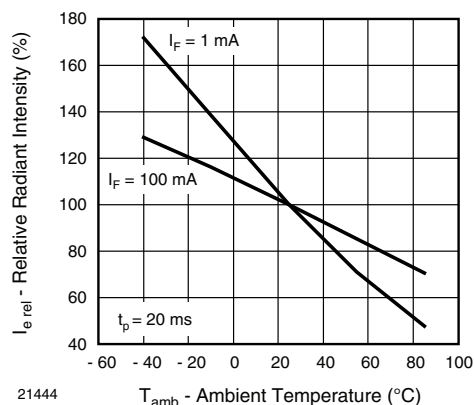


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

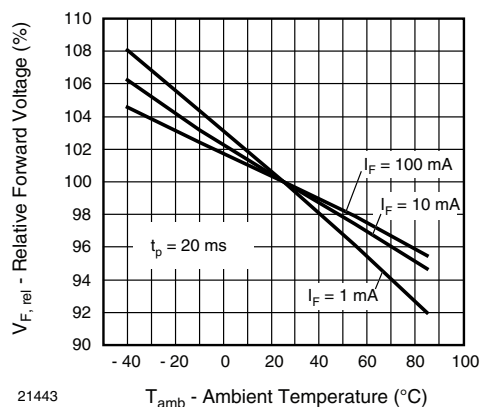


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

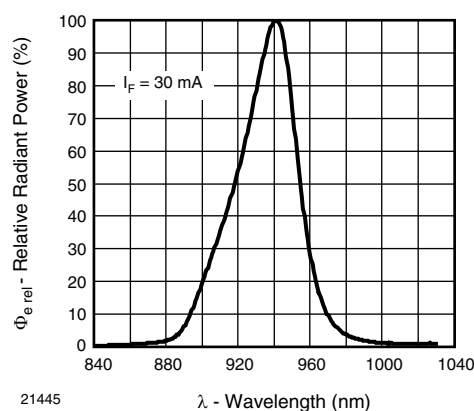


Fig. 7 - Relative Radiant Power vs. Wavelength

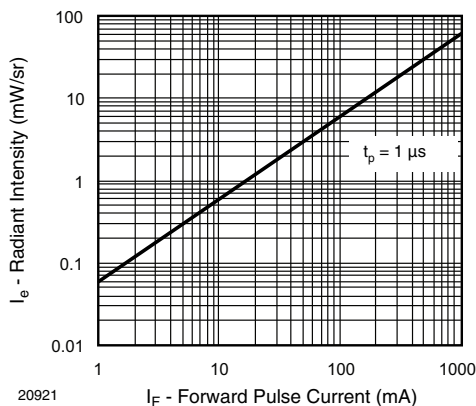


Fig. 5 - Radiant Intensity vs. Forward Current

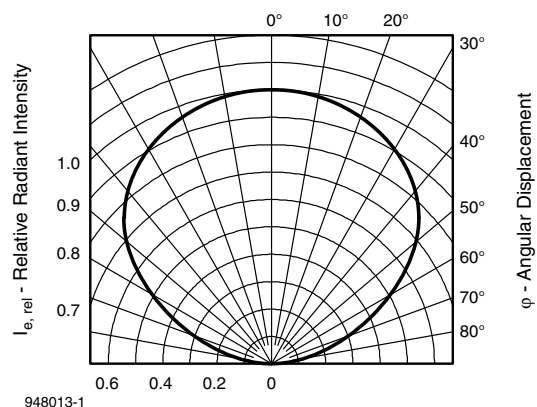


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

## REFLOW SOLDER PROFIEL

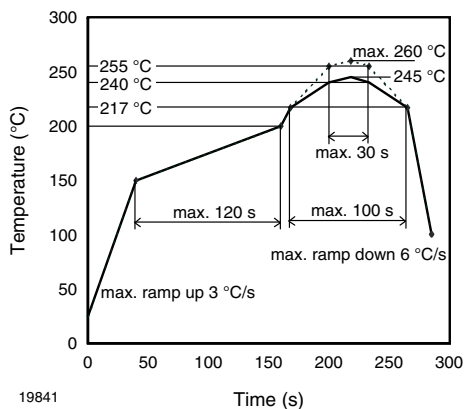


Fig. 9 - Lead (Pb)-free Reflow Solder Profile  
According to J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

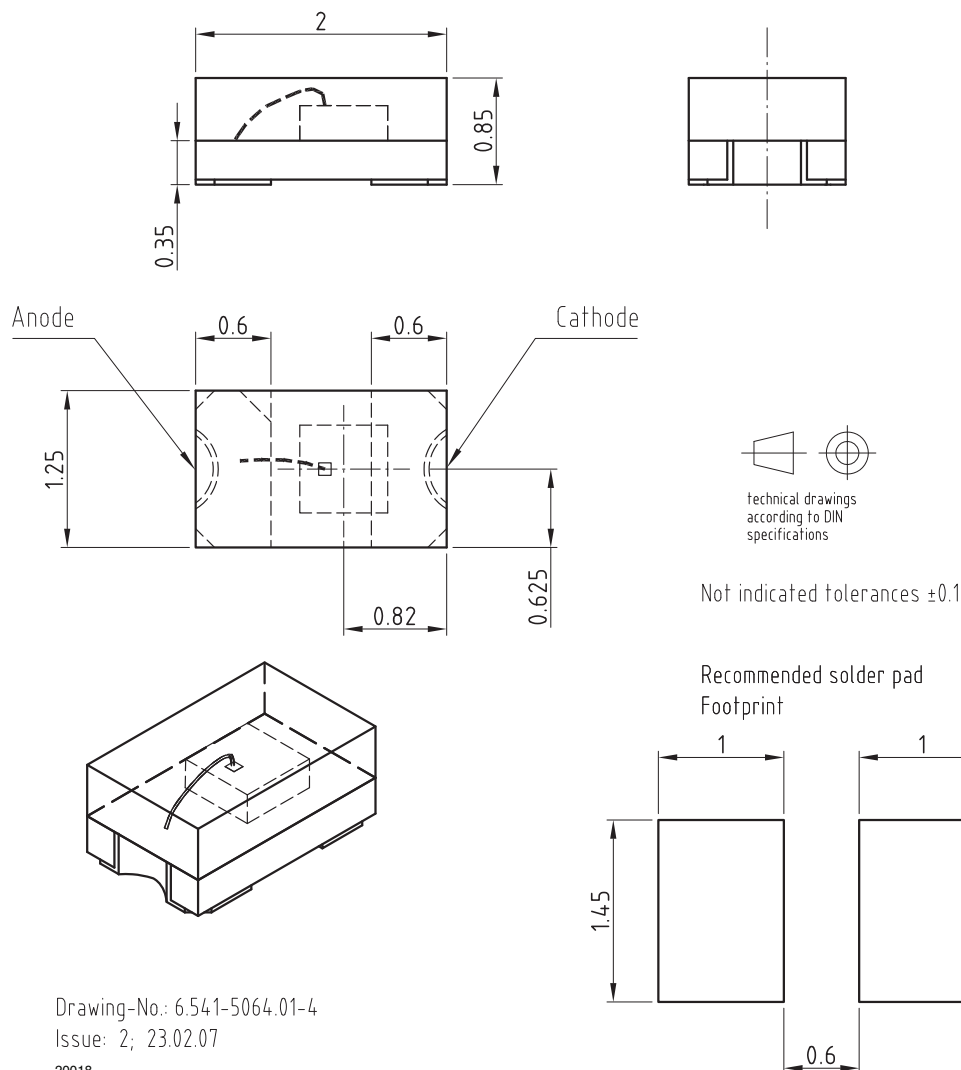
Floor life: 72 h

Conditions:  $T_{amb} < 30\text{ °C}$ ,  $RH < 60\%$

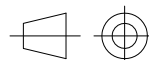
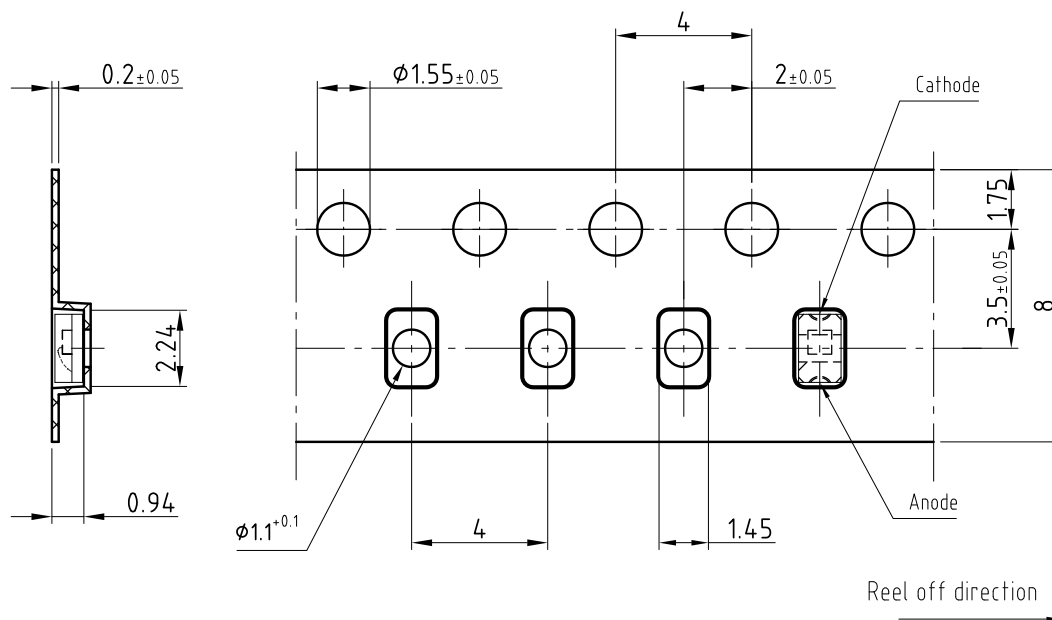
## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at  $40\text{ °C} (+ 5\text{ °C})$ ,  $RH < 5\%$ .

## PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5064.01-4  
Issue: 2; 23.02.07  
20018

**BLISTER TAPE DIMENSIONS** in millimeters

technical drawings  
according to DIN  
specifications

Drawing-No.: 9.700-5311.01-4

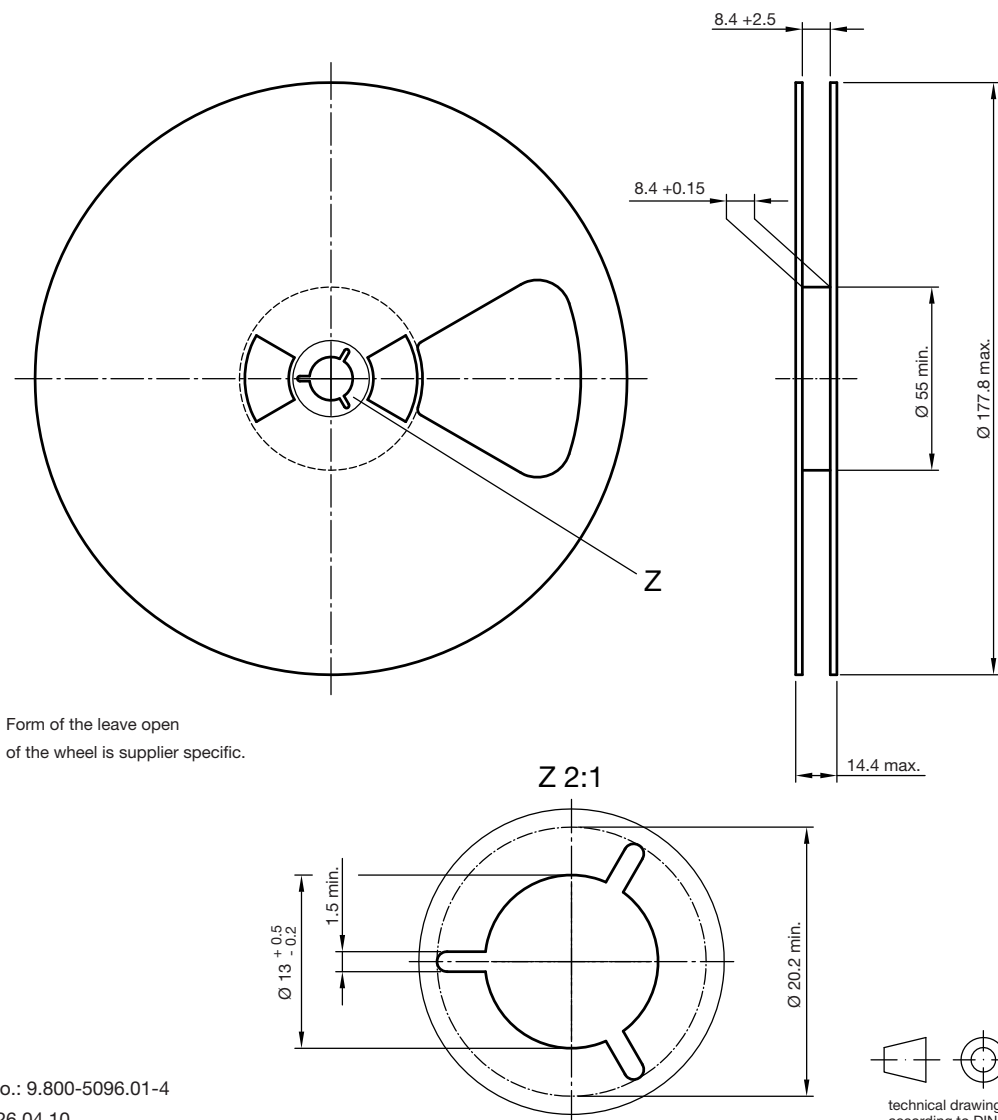
Issue: 1; 23.02.07

21501

Not indicated tolerances  $\pm 0.1$



**REEL DIMENSIONS** in millimeters



Drawing-No.: 9.800-5096.01-4  
Issue: 2; 26.04.10  
20875



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